

Abstract

The operability of light-based semiconductor die analysis is enhanced using a method and arrangement that directs light between a light source and a die. In one example embodiment of the present invention, a light source is directed to a die in a 5 semiconductor analysis arrangement using a fiber optic cable. The analysis arrangement is adapted to use light received via the fiber optic cable to analyze the die. The analysis includes one or more light-based applications, such as stimulating a selected portion of the die with the light and detecting a response therefrom. In this manner, light can be directed to a die in a variety of analysis implementations, such as 10 for analyzing a die in a test chamber.